# 2SC4805G

# Silicon NPN epitaxial planar type

For 2 GHz band low-noise amplification

### Features

- $\bullet$  High transition frequency  $f_{T}$
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

Parameter	Symbol	Rating	Unit				
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	15	V				
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	10	V				
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	2	V				
Collector current	I <sub>C</sub>	65	mA				
Collector power dissipation	P <sub>C</sub>	150	mW				
Junction temperature	Tj	150	°C				
Storage temperature	T <sub>stg</sub>	-55 to +150	°C				

### Absolute Maximum Ratings $T_a = 25^{\circ}C$

- Package
- Code SMini3-F2
- Marking Symbol: 3S
- Pin Name
  - 1: Base
  - 2: Emitter
- 3: Collector

### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

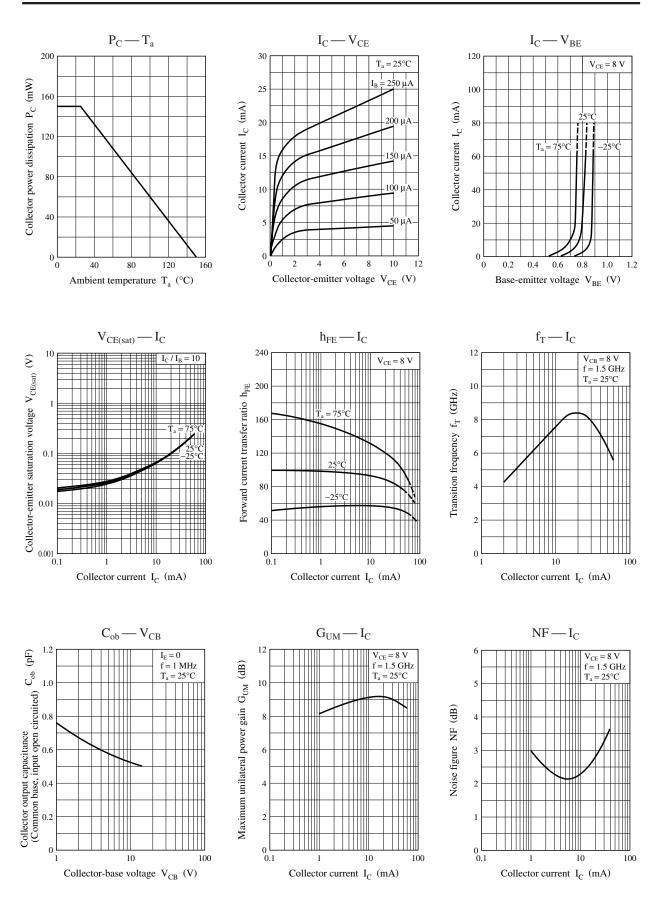
Parameter	Symbol	Conditions		Тур	Мах	Unit
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = 10 \text{ V}, I_E = 0$			1	μA
Emitter-base cutoff current (Collector open)	I <sub>EBO</sub>	$V_{EB} = 1 V, I_C = 0$			1	μA
Forward current transfer ratio *	h <sub>FE</sub>	$V_{CE} = 8 V, I_C = 20 mA$	50		300	
Transition frequency	f <sub>T</sub>	$V_{CE} = 8 V, I_C = 15 mA, f = 1.5 GHz$	7.0	8.5		GHz
Collector output capacitance (Common base, input open circuited)	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		0.6	1.0	pF
Forward transfer gain	$ S_{21e} ^2$	$V_{CE} = 8 V, I_C = 15 mA, f = 1.5 GHz$	7	9		dB
Maximum unilateral power gain	G <sub>UM</sub>	$V_{CE} = 8 V, I_C = 15 mA, f = 1.5 GHz$		10		dB
Noise figure	NF	$V_{CE} = 8 V, I_C = 7 mA, f = 1.5 GHz$		2.2	3.0	dB

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. 2. \*: Rank classification

Rank	Q	R	S	No-rank
h <sub>FE</sub>	50 to 120	100 to 170	150 to 300	50 to 300
Marking symbol	3SQ	3SR	388	3S

Product of no-rank is not classified and have no indication for rank.

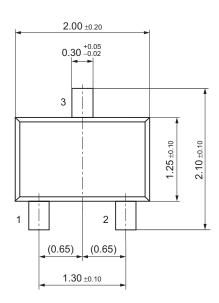
#### Publication date: May 2007

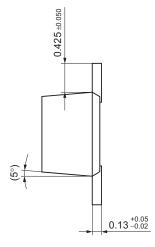


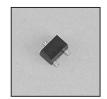
# **Panasonic**

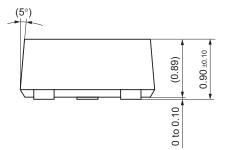
## SMini3-F2

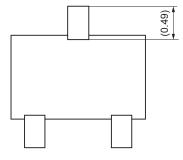
### Unit: mm











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